

PCN Number:	20131209002		PCN Date:	12/27/2013	
Title:	Qualification of RFAB and JCAP as additional Fab site and Assembly/Test site options for select devices in the LBC8LV Fab process.				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept: Quality Services	
*Proposed 1st Ship Date:	03/27/2014	Estimated Sample Availability:	Date Provided at Sample request		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
PCN Details					
Description of Change:					
<p>This change notification is to announce the addition of RFAB and JCAP as additional Fab site and Assembly/Test site options for select devices in the LBC8 Fab Process. There are no changes to the Bill of Materials as a result of this change. Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>					
Group 1 (Fab Site):					
Current Site/Process/Wafer Diameter		Additional Site/Process/Wafer Diameter			
UMC-F8E/LBC8LV Process/200mm		RFAB/LBC8LV Process/300mm			
Group 2 (Assembly Site):					
TI Clark - Philippines	Assembly Site Origin (22L)	ASO: QAB			
JCAP	Assembly Site Origin (22L)	ASO: JCP			
<p>The LBC8 process was qualified at RFAB on 2/14/2013. The WCSP package was qualified at JCAP on 2/19/2013. Qualification results are shown below.</p>					
Reason for Change:					
Continuity of supply.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Fab Site					
Current Chip Site	Chip Site Code (20L)	Chip Country Code (21 L)			
UMC-F8E	CSO: U8E	TWN			
New Chip Site	Chip Site Code (20L)	Chip Country Code (21 L)			
RFAB	CSO: RFB	USA			
Assembly Site					
Current Assembly Site	Assembly Site Origin (22L)	ASO: QAB			
Clark-AT	Assembly Site Origin (22L)	ASO: QAB			
New Assembly Site	Assembly Site Origin (22L)	ASO: JCP			
JCAP-AT	Assembly Site Origin (22L)	ASO: JCP			

The symbolization will remain the same.
 ASSEMBLY SITE CODES: TI CLARK =I, JCAP = P

Sample Product Shipping Label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:
 OPT: ITEM: 39
LBL: 5A (L)T0:1750

(Pb) G4
 (1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected Group 1 (Fab Site):

DRV2604YZFR	DRV2604YZFT	DRV2605YZFR	DRV2605YZFT
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Product Affected Group 2 (Assembly and Test Site):

DRV2604YZFR	DRV2604YZFT	DRV2605YZFR	DRV2605YZFT
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Qualification Data Group 1: Approved 2/14/2013

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Device 1: SH8350BCA0PAPG4 (MSL LEVEL3-260C)

Wafer Fab Site:	RFAB	Wafer Fab Process:	LBC8
Wafer Diameter:	300mm		

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
Life Test	125C (1000 hours)	77/0	76/0	71/0
Electrical Characterization	Per datasheet specification	Pass	-	-
**Biased HAST	130C/85%RH (96 hours)	77/0	77/0	77/0
**Autoclave	121C (96 hours)	77/0	77/0	77/0
**Temp Cycle	-65/150C (500 cycles)	77/0	77/0	77/0
**High Temp Storage Bake	170C (420 hours)	77/0	77/0	77/0
ESD CDM	Per datasheet	5/0	5/0	5/0
ESD HBM	Per datasheet	5/0	5/0	5/0
Latch-up	Per JESD78	6/0	6/0	6/0

**Preconditioning: Level 3-260C

Qualification Data Group 2: Approved 2/19/2013

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Device 1: CD3230A0YFF (MSL LEVEL1-260C)

Assembly Site:	JCAP	Bump Composition:	SnAgCu		
# Pins-Designator, Family:	130-YFF, WCSP	Bump Diameter:	0.25mm		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Sample Size / Fail			
		Lot#1	Lot#2	Lot#3	
**Unbiased HAST	130C/85%RH (96 hours)	85/0	82/0	78/0	
**High Temp Storage Bake	170C (420 hours)	84/0	80/0	78/0	
**Biased HAST	130C/85%RH (96 hours)	85/0	-	-	
Life Test	125C (1000 hours)	80/0	-	-	
**Temp Cycle	-55/125C (1000 cycles)	85/0	85/0	78/0	
**Preconditioning: Level 1-260C					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com